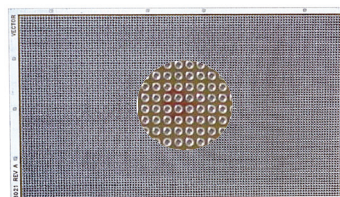


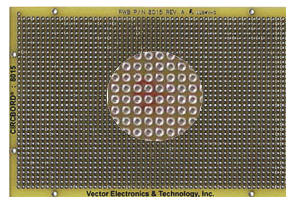
Vectorbord® Circbord™ offers an assortment of basic printed circuit pattern prototyping boards for solder or wire-wrap connections. A wide selection of tin or gold plated terminals and wire-wrap pins located on pages 70-72.

**Round Pads-Per-Hole with .025" Holes, .050" Grid**



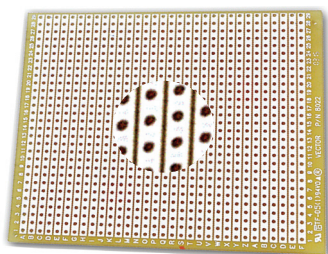
**8021 3.94"Hx6.3"Lx .062" TH**  
(100MM x 160MM)  
3U Eurocard size  
0.050" grid "M" pattern, 0.024" diameter holes with 0.034" diameter pads, both sides.  
Copper plated-thru- holes, solder coated pattern.  
Material: FR4  
Inbord Pin: K36C

**Round Pads-Per-Hole with 0.042" Holes, .100" Grid**

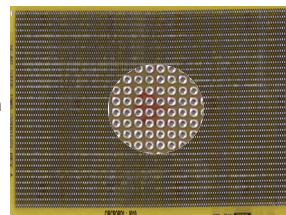


**8015 4.0"Hx6.0"L x .062" TH**  
0.100" grid Pad-Per-Hole Pattern. .042" holes plated thru with .080" isolated solder pad around each hole on both sides.  
16-Pin DIP= 72.  
Material: FR4.  
WW Terminals: T44, T46, T49, T68.  
Solder Terminals: T42-1, K24C  
WW Socket Pin: R32

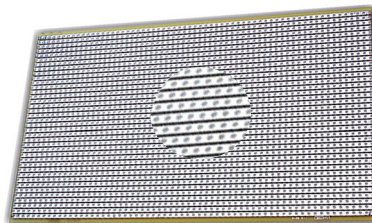
**Strip Busses with 0.042" Holes, .100" Grid**



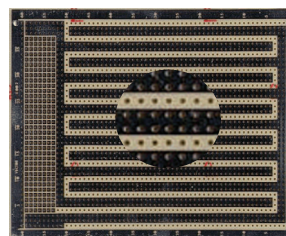
**8022 3.0"Hx3.5"L x .062" TH**  
0.100" grid, economical size, 32 stripline tracks (in 3.0" direction), 29 holes per track.  
For common bus or signal lines or break pad at any desired number of holes.  
Solder coated pattern, single side only  
Material: FR4  
WW Terminals: T44, T46, T49, T68  
Solder Terminals: T42-1  
WW Socket Pin: R32



**8010 4.0"Hx12.860"L x .062" TH**  
0.100" grid Pad-Per-Hole Pattern on both sides. Board approximates MACII specification.  
.042" holes plated thru with .080" isolated solder pad around each hole on both sides.  
16-Pin DIP= 124.  
Material: FR4.  
WW Terminals: T44, T46, T49, T68.  
Solder Terminals: T42-1  
WW Socket Pin: R32

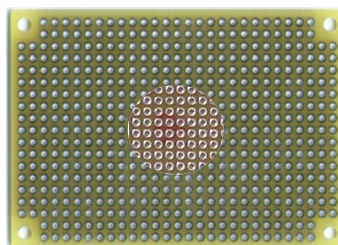


**8019 3.94"H x 6.3"L x .062" TH**  
3U Eurocard size  
0.100" grid, economical size, 38 lengthwise stripline tracks (in 6.3" direction), 63 holes per track. For common bus or signal lines, or break pad at any desired number of holes.  
Copper plated-thru-holes, solder coated pattern.  
Material: FR4  
WW Terminals: T44, T46, T49, T68  
Solder Terminals: T42-1  
WW Socket Pin: R32

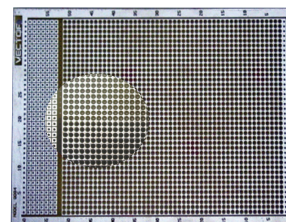


**8002 4.5"Hx6.5"L x .062" TH**  
0.100" grid Interleave Bus Pattern on one side only, no plating or etch on reverse side. Components can be mounted on 0.3", 0.6" and 0.9" lead spacing. 0.042" holes with Power/GND busses. I/O area with square pads for connector mounting.  
Solder coated pattern.  
Material: CEM-1  
WW Terminals: T44, T46, T49, T68.  
Solder Terminals: T42-1  
WW Socket Pin: R32

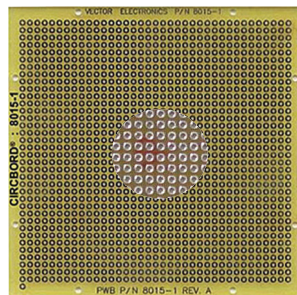
**Round Pads-Per-Hole with 0.042" Holes, .100" Grid**



**8029 2.0"Hx3.0"L x .062" TH**  
0.100" grid, Pad-Per-Hole Pattern on both sides, 0.042" holes plated-thru copper.  
Small economical size ideal for mounting on standoffs. Solder coated pattern.  
16-Pin DIP capacity = 24  
Material: FR4  
WW Terminals: T44, T46, T49, T68  
Solder Terminals: T42-1  
WW Socket Pin: R32



**8004 4.50"Hx6.50"Lx.062"TH**  
0.100" grid single sided w/overall Ground Plane only Single-sided with no etch & plating on reverse side  
.042" holes with .080" clearance around each hole. I/O area w/square solder pads for mounting connector  
16-Pin DIP = 50  
Material: FR-4  
WW Terminals: T44, T 46, T49, T68  
Solder Terminals: T42-1  
WW Socket Pin: R32



**8015-1 4.0"Hx4.0"L x .062" TH**  
0.100" grid Pad-Per-Hole 1 sided Pattern  
No etch or plating on reverse side  
.042" holes with isolated round pad around each hole  
16-Pin DIP= 72  
Material: FR4  
WW Terminals: T44, T46, T49, T68  
Solder Terminals: T42-1, K24C  
WW Socket Pin: R32